RTMBF305 – RTMBF310

FAST RECOVERY SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER



Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability

Mechanical Data

High Surge Current Capability

MIL-STD-202, Method 208

Mounting Position: Any Marking: Type Number

Polarity: As Marked on Case

- Designed for Surface Mount Application
- Plastic Material UL Flammability 94V-O

Case: SOPA-4, ABS, Molded Plastic

Terminals: Plated Leads Solderable per

Lead Free: For RoHS / Lead Free Version

TMBF .205 (5.2) .098 (0.25) .006(0.17) $.\overline{189(4.8)}$.350(8.9) .315 (8.0) .335(8.5) .299 (7.6) .064(1.4) .032(0.8).024 (0.6) .043(1.1) .008(0.2) .035(0.9) .268 (6.8) .252(6.4) .012(0.3) $.\overline{008(0.2)}$.059(1.5) .051(1.3) Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics @T_Aerwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	RTMBF 305	RTMBF 31	RTMBF 32	RTMBF 34	RTMBF 36	RTMBF 38	RTMBF 310	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	VR(RMS)	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) $@T_A = 40^{\circ}C$ Average Rectified Output Current (Note 2) $@T_A = 40^{\circ}C$	lo	3.0							А
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	105							A
I^2 t Rating for Fusing (t < 8.3ms)	l ² t	5.0							A ² s
Forward Voltage per element $@I_F = 3.0A$	VFM	1.25							V
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_A = 125^{\circ}C$	Iгм	5.0 200							μA
Reverse Recovery Time (Note 4)	trr		150 250						nS
Typical Junction Capacitance per leg (Note 3)	Cj	13						pF	
Typical Thermal Resistance per leg (Note 1)	RθJA RθJL	62.5 25						°C/W	
Operating and Storage Temperature Range	Тj, Tsтg	-55 to +150							°C

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

4. Measured with IF = 0.5A, IR = 1.0A, IRR = 0.25A. See figure 5.

